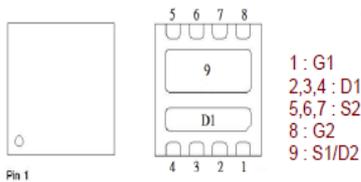


# PE674DT

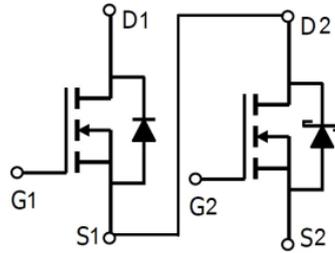
## Dual N-Channel Enhancement Mode MOSFET

### PRODUCT SUMMARY

	$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$
Q2	30V	7mΩ @ $V_{GS} = 10V$	39A
Q1	30V	10.5mΩ @ $V_{GS} = 10V$	31A



PDFN 3X3S



### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25\text{ °C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	Q2	Q1	UNITS	
Drain-Source Voltage	$V_{DS}$	30	30	V	
Gate-Source Voltage	$V_{GS}$	±20	±20		
Continuous Drain Current <sup>3</sup>	$T_C = 25\text{ °C}$	39	31	A	
	$T_C = 100\text{ °C}$	25	20		
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	50	45		
Continuous Drain Current <sup>3</sup>	$T_A = 25\text{ °C}$	12	9.5		
	$T_A = 70\text{ °C}$	10	7.6		
Avalanche Current	$I_{AS}$	23	17.5		
Avalanche Energy	$L = 0.1\text{mH}$	$E_{AS}$	26.4	15.3	mJ
Power Dissipation	$T_C = 25\text{ °C}$	$P_D$	20	19	W
	$T_C = 100\text{ °C}$		8.3	7.6	
Power Dissipation	$T_A = 25\text{ °C}$	$P_D$	2.2	1.7	
	$T_A = 70\text{ °C}$		1.4	1.1	
Operating Junction & Storage Temperature Range	$T_J, T_{stg}$	-55 to 150		°C	

### THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient <sup>2</sup>	$R_{\theta JA}$ Q2		56	°C / W
	$R_{\theta JA}$ Q1		72	
Junction-to-case	$R_{\theta JC}$ Q2		6	
	$R_{\theta JC}$ Q1		6.5	

<sup>1</sup>Pulse width limited by maximum junction temperature  $T_{J(MAX)}=150\text{ °C}$ .

<sup>2</sup>The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25\text{ °C}$ . The value in any given application depends on the user's specific board design.

<sup>3</sup>Package limitation current is Q2= 19A , Q1= 11A.

# PE674DT

## Dual N-Channel Enhancement Mode MOSFET

### ELECTRICAL CHARACTERISTICS (T<sub>J</sub> = 25 °C, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	Q2	30		V
			Q1	30		
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	Q2	1.3	1.75	2.3
			Q1	1.3	1.75	2.3
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	Q2			±100
			Q1			±100
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 24V, V <sub>GS</sub> = 0V	Q2			1
			Q1			1
		V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 55 °C	Q2			10
			Q1			10
Drain-Source On-State Resistance <sup>1</sup>	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 10A	Q2		6.7	9.5
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 9A	Q1		10.2	15.5
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 10A	Q2		5	7
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 9.5A	Q1		7.5	10.5
Forward Transconductance <sup>1</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 10A	Q2		66	S
		V <sub>DS</sub> = 5V, I <sub>D</sub> = 9.5A	Q1		50	
<b>DYNAMIC</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 15V, f = 1MHz	Q2		961	pF
			Q1		627	
Output Capacitance	C <sub>oss</sub>		Q2		185	
			Q1		129	
Reverse Transfer Capacitance	C <sub>rss</sub>		Q2		121	
			Q1		97	
Total Gate Charge <sup>2</sup>	Q <sub>g</sub>	V <sub>GS</sub> = 10V	Q2		19.3	nC
			Q1		14	
		V <sub>GS</sub> = 4.5V	Q2		11.2	
			Q1		7.8	
Gate-Source Charge <sup>2</sup>	Q <sub>gs</sub>	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 10V, I <sub>D</sub> = 10A	Q2		2.1	
Q1			1.6			
Gate-Drain Charge <sup>2</sup>	Q <sub>gd</sub>	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 10V, I <sub>D</sub> = 9.5A	Q2		5.9	
			Q1		4.1	

## PE674DT

### Dual N-Channel Enhancement Mode MOSFET

Turn-On Delay Time <sup>2</sup>	$t_{d(on)}$	Q2 $V_{DS} = 15V$ , $I_D \cong 10A, V_{GS} = 10V, R_{GEN} = 6\Omega$ Q1 $V_{DS} = 15V$ , $I_D \cong 9.5A, V_{GS} = 10V, R_{GEN} = 6\Omega$	Q2		13		nS		
Rise Time <sup>2</sup>	$t_r$		Q1		12				
Turn-Off Delay Time <sup>2</sup>	$t_{d(off)}$		Q2		57				
			Q1		48				
Fall Time <sup>2</sup>	$t_f$		Q2		35				
			Q1		27				
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (<math>T_J = 25^\circ C</math>)</b>									
Continuous Current <sup>3</sup>	$I_S$			Q2				16	A
		Q1				17			
Forward Voltage <sup>1</sup>	$V_{SD}$		Q2			1.2	V		
			Q1			1.1			
Reverse Recovery Time	$t_{rr}$	Q2 $I_F = 10A, di_F/dt = 100A/\mu S$ Q1 $I_F = 9.5A, di_F/dt = 100A/\mu S$	Q2		12		nS		
Reverse Recovery Charge	$Q_{rr}$		Q2		3				
			Q1		3		nC		

<sup>1</sup>Pulse test : Pulse Width  $\leq 300 \mu\text{sec}$ , Duty Cycle  $\leq 2\%$ .

<sup>2</sup>Independent of operating temperature.

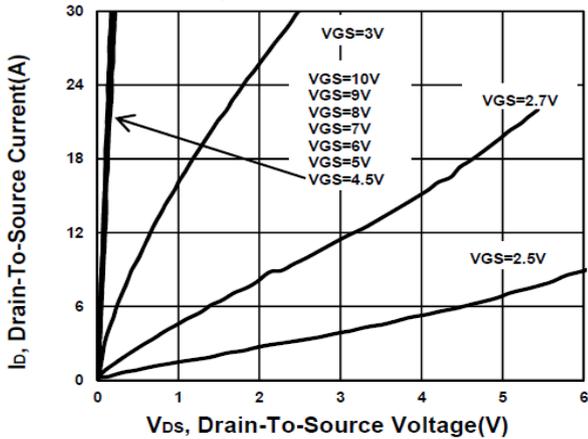
<sup>3</sup>Package limitation current is Q2=19A , Q1=11A.

# PE674DT

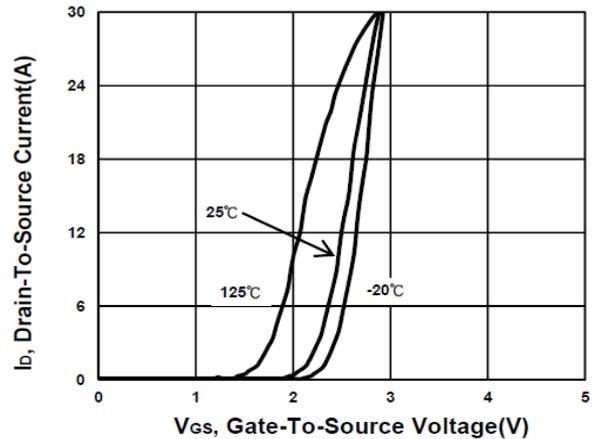
## Dual N-Channel Enhancement Mode MOSFET

**Q2**

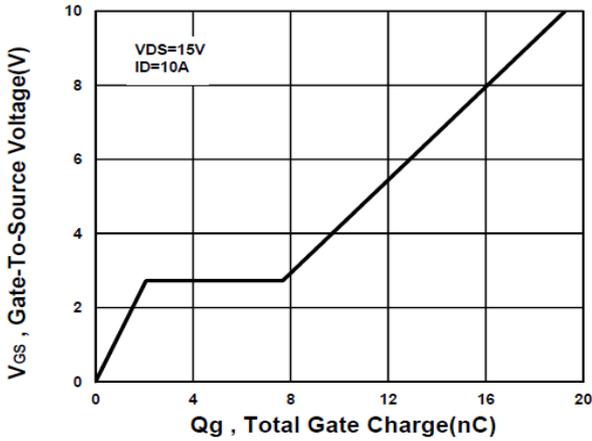
**Output Characteristics**



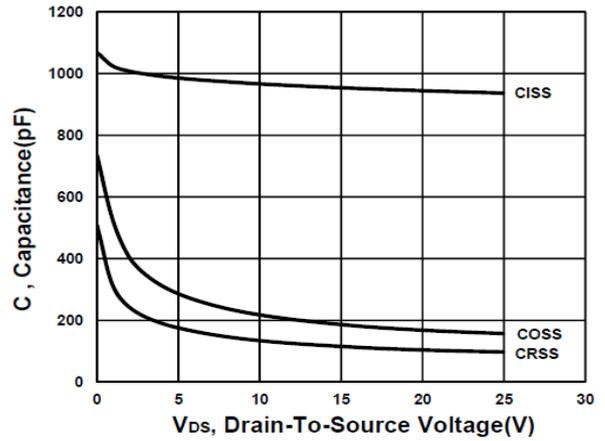
**Transfer Characteristics**



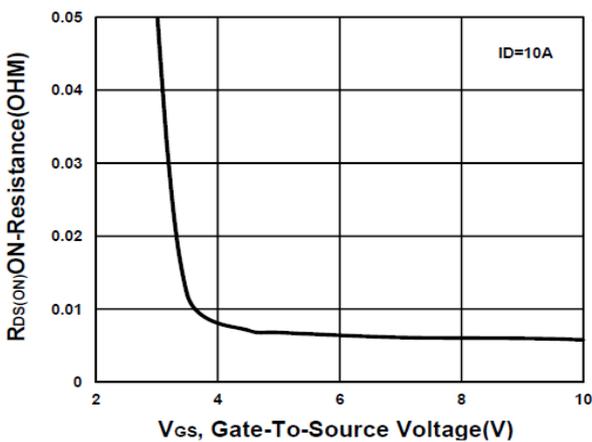
**Gate charge Characteristics**



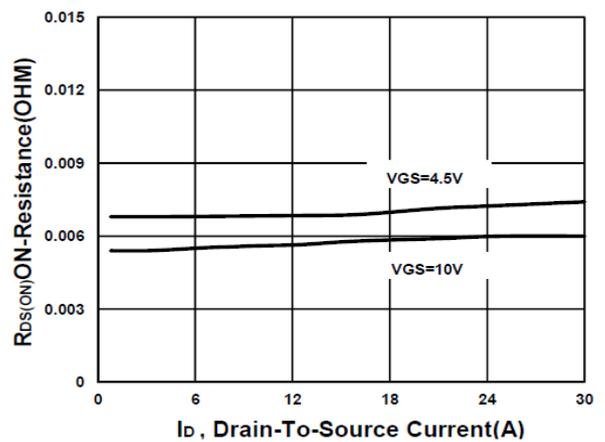
**Capacitance Characteristic**



**On-Resistance VS Gate-To-Source**



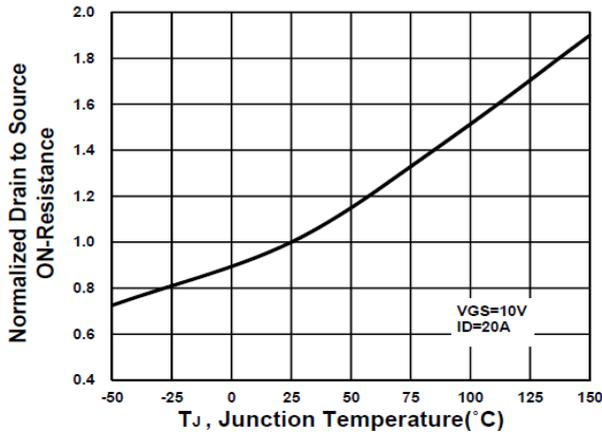
**On-Resistance VS Drain Current**



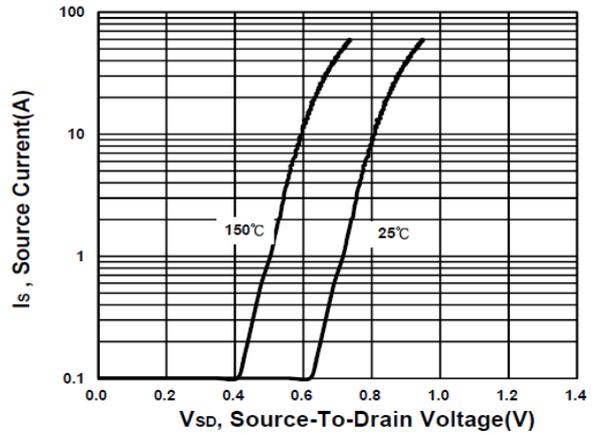
# PE674DT

## Dual N-Channel Enhancement Mode MOSFET

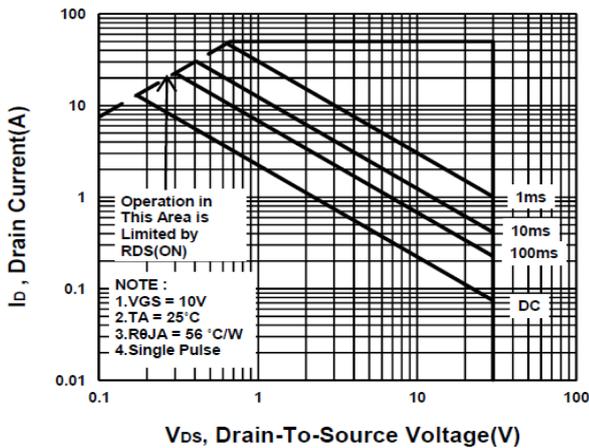
**On-Resistance VS Temperature**



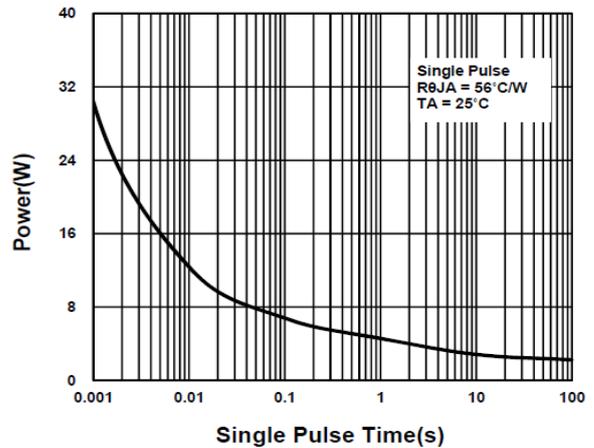
**Source-Drain Diode Forward Voltage**



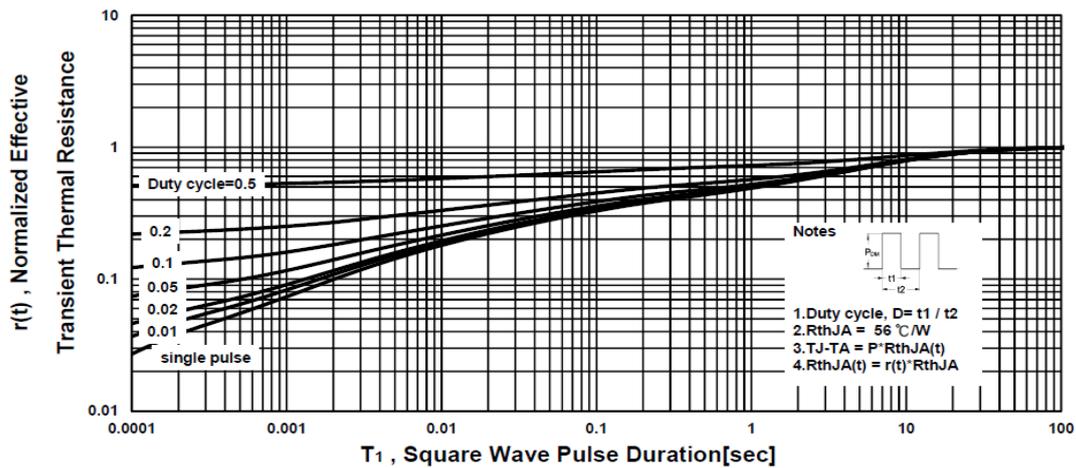
**Safe Operating Area**



**Single Pulse Maximum Power Dissipation**



**Transient Thermal Response Curve**

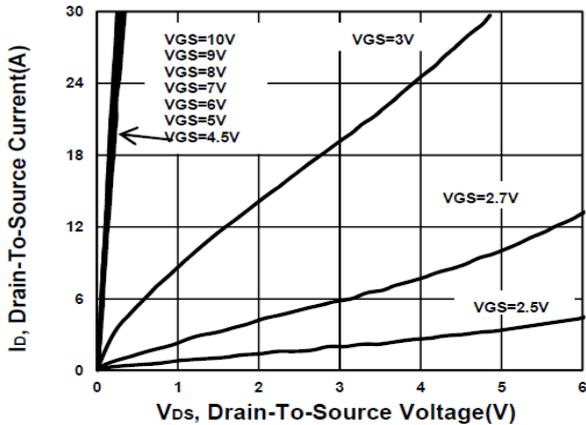


# PE674DT

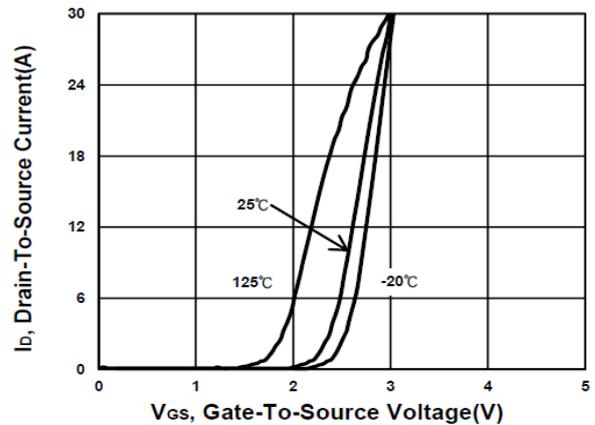
## Dual N-Channel Enhancement Mode MOSFET

**Q1**

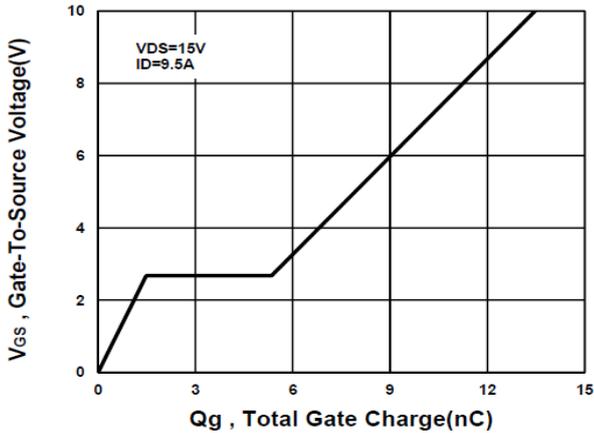
**Output Characteristics**



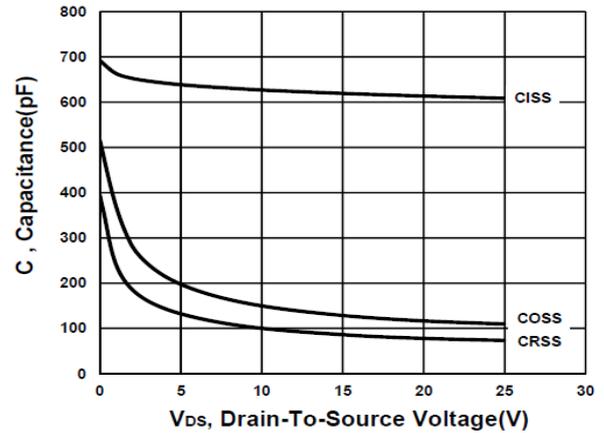
**Transfer Characteristics**



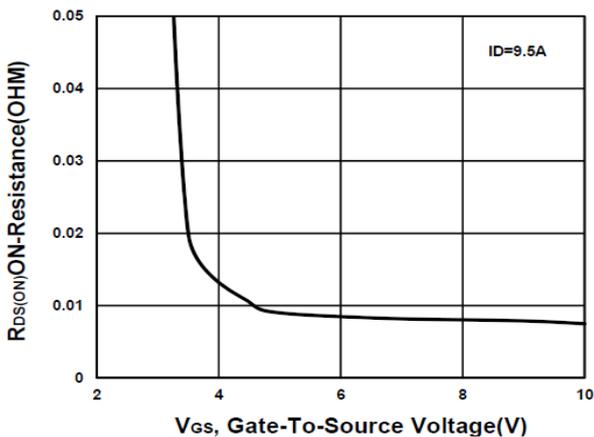
**Gate charge Characteristics**



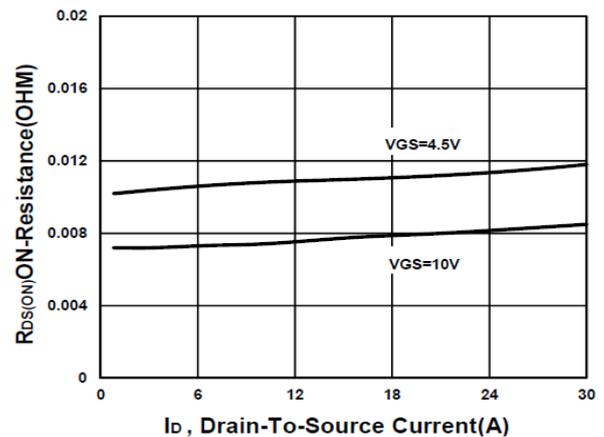
**Capacitance Characteristic**



**On-Resistance VS Gate-To-Source**



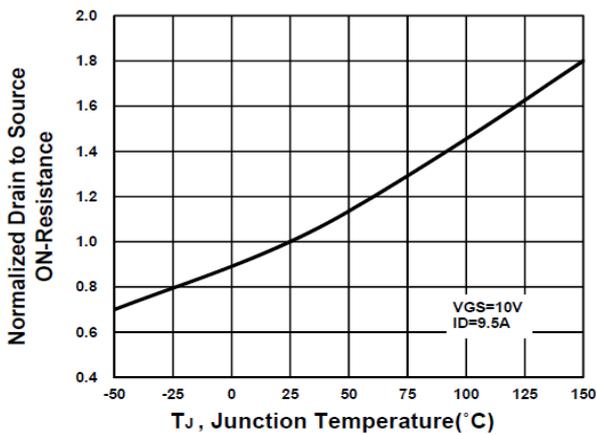
**On-Resistance VS Drain Current**



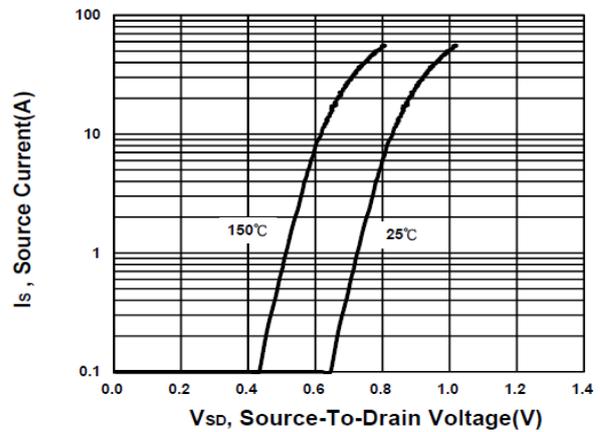
# PE674DT

## Dual N-Channel Enhancement Mode MOSFET

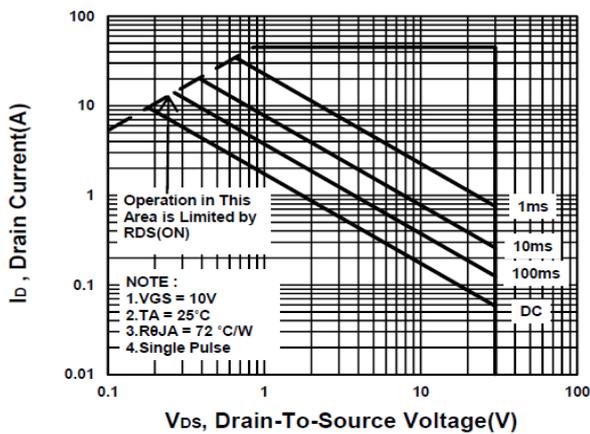
**On-Resistance VS Temperature**



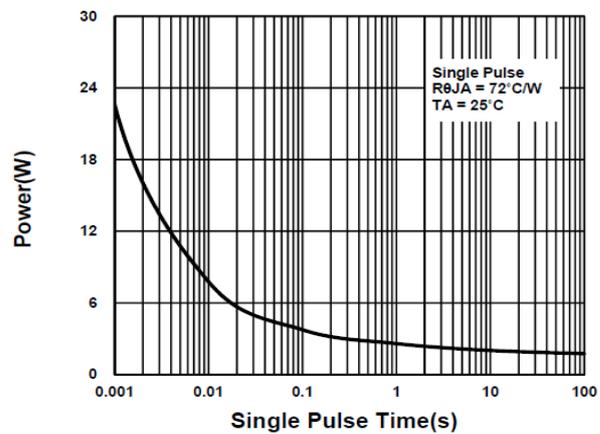
**Source-Drain Diode Forward Voltage**



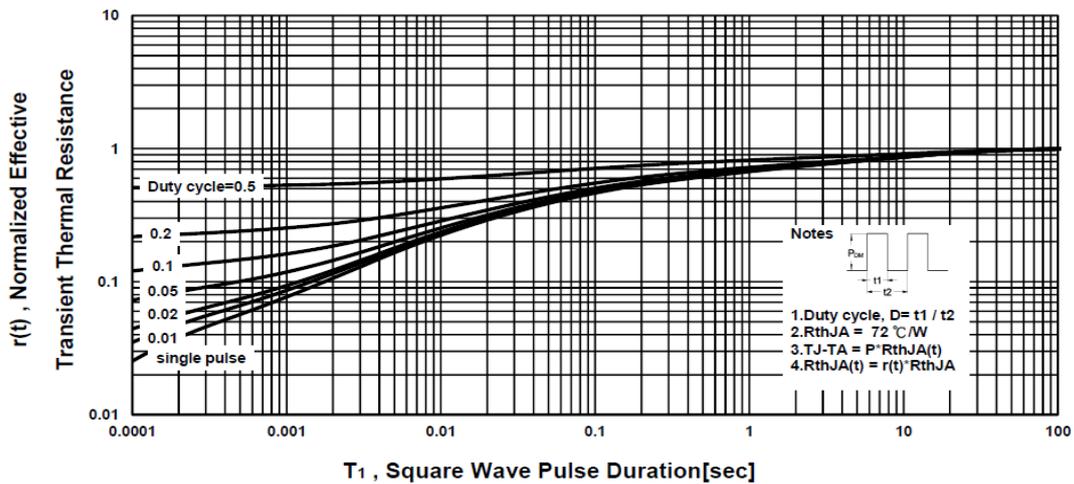
**Safe Operating Area**



**Single Pulse Maximum Power Dissipation**



**Transient Thermal Response Curve**



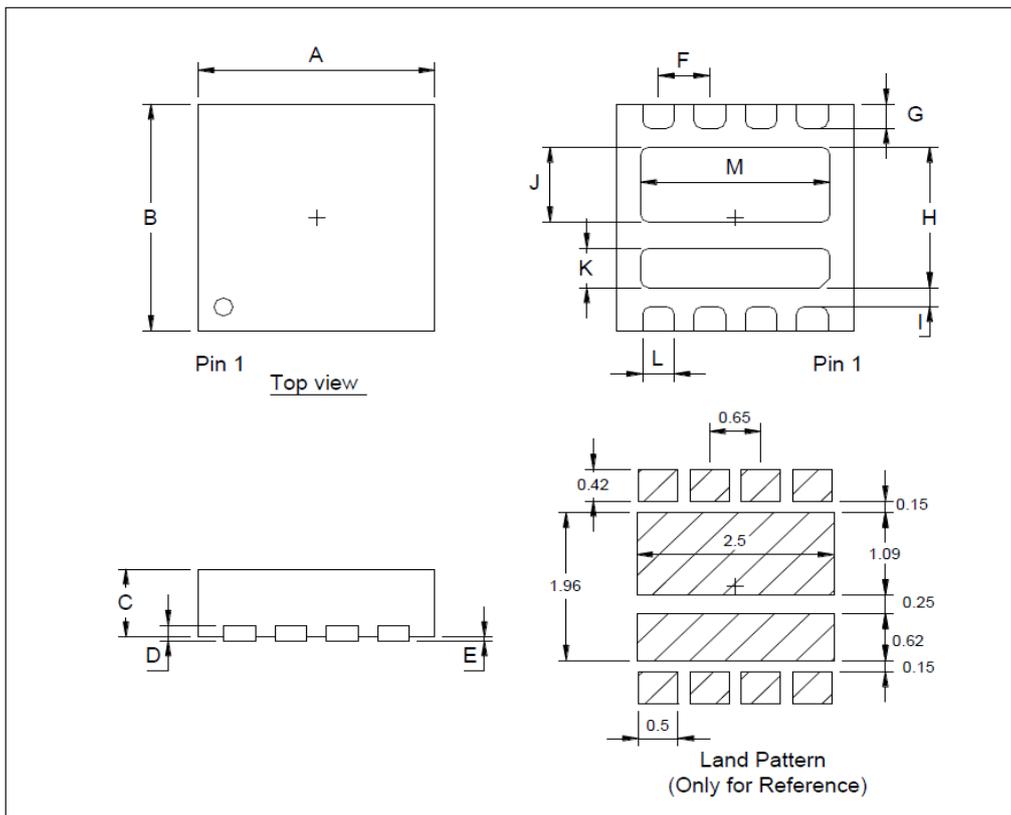
# PE674DT

## Dual N-Channel Enhancement Mode MOSFET

### Package Dimension

### PDFN 3x3S(上下 Dual) MECHANICAL DATA

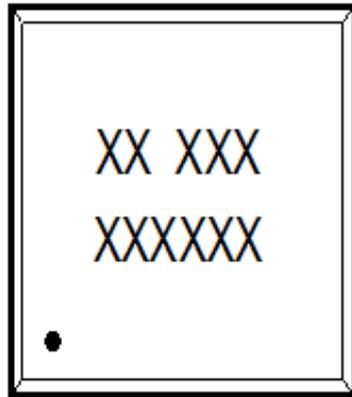
Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	2.9	3	3.1	I		0.25	
B	2.9	3	3.1	J	0.94	0.99	1.04
C	0.8	0.85	0.9	K	0.47	0.52	0.57
D	0.195	0.203	0.211	L	0.35	0.4	0.45
E	0		0.05	M	2.35	2.40	2.45
F		0.65					
G	0.27	0.32	0.37				
H		1.86					



# PE674DT

## Dual N-Channel Enhancement Mode MOSFET

### A. Marking Information(此产品代码为: M6)

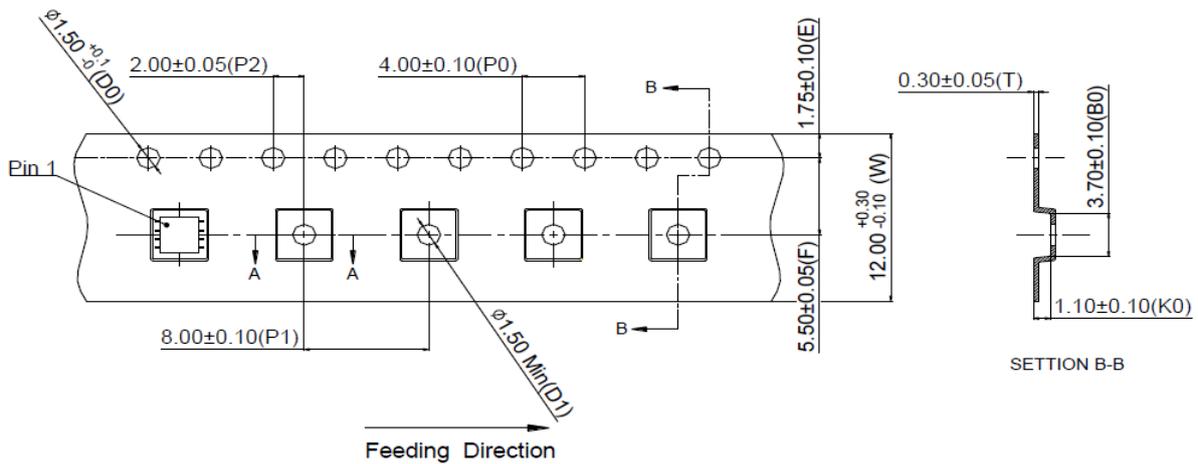


XX(前两码):产品代码

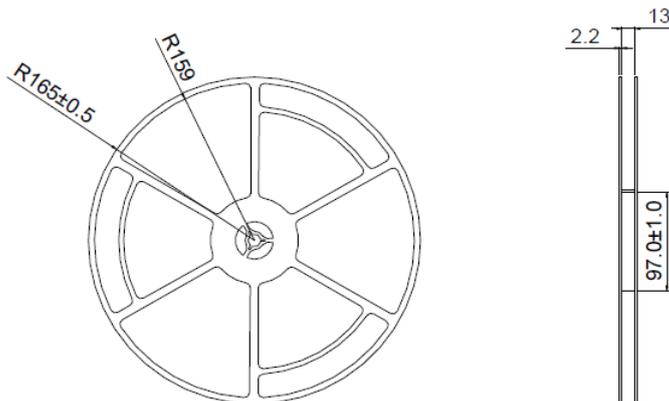
XXX

XXXXXX(后九码):LOT.NO

### B. Tape & Reel Information: 5000pcs/Reel



SECTION B-B

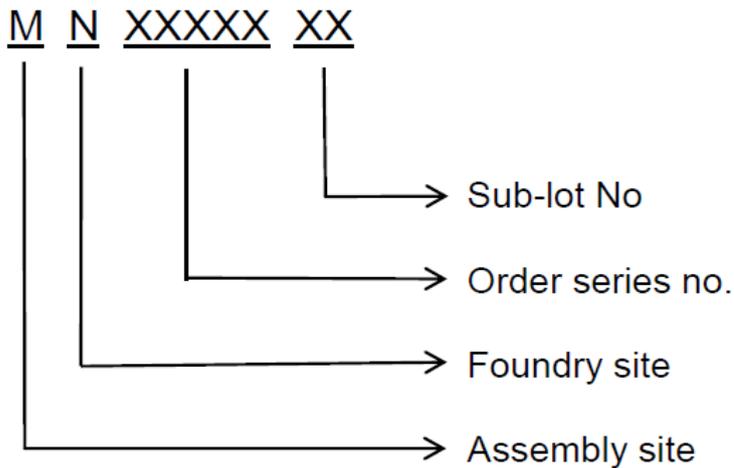


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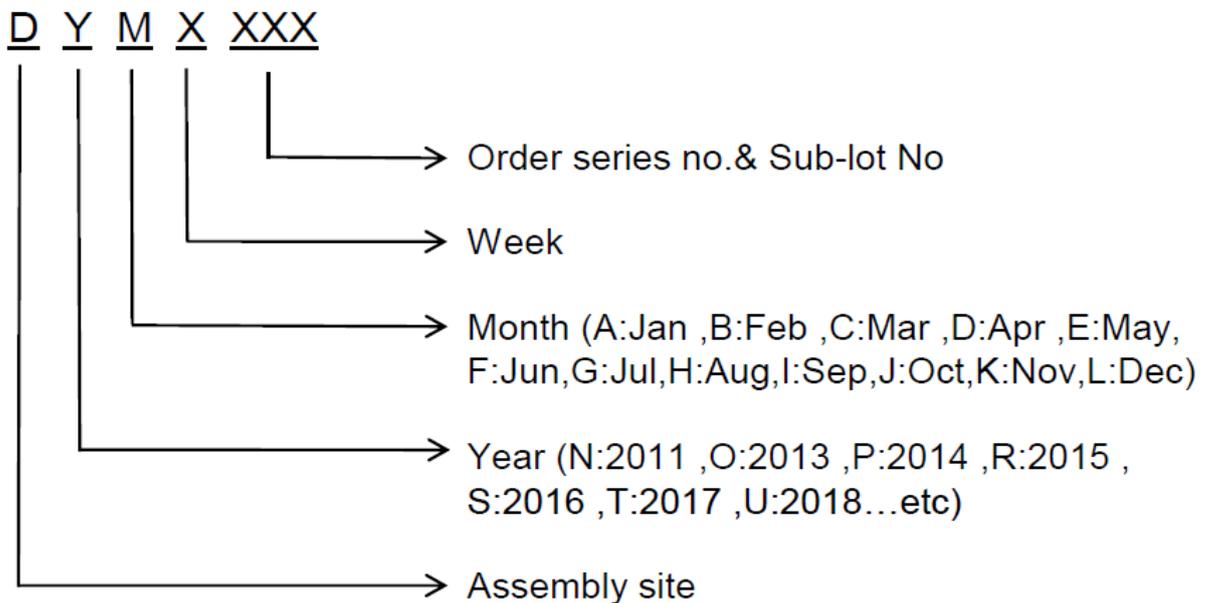
## Dual N-Channel Enhancement Mode MOSFET

### C. Lot No.&Date Code rule

#### 1.Lot No.



#### 2.Date Code



# PE674DT

## Dual N-Channel Enhancement Mode MOSFET

### D.Label rule

标签内容(Label content)



1	Label Size	30 * 90 mm
2	Font style	Times New Roman or Arial (或可区分英文”0”和数字”0”，”G和”Q”的字型即可)
3	U-NIKC	Height: 4 mm
4	Package	Height: 2 mm
5	Date	Height: 2 mm Shipping date: YYYY/MM/DD, ex. 2008/09/12
6	Device	Height: 3 mm (Max: 16 Digit)
7	Lot	Height: 3 mm (Max: 9 Digit) Sub lot
8	D/C	Height: 3 mm (Max: 7 Digit)
9	QTY	Height: 3 mm (Max: 6 Digit) Thousand mark is no needed
10	RoHS label	 long axis: 12 mm minor axis:6 mm bottom color: White Font color: Black Font style: Arial
11	Halogen Free label	 Diameter: 10 mm bottom color: Green Font color: Black Font style: Arial
12	Scan information	Device / Lot / D/C / QTY , Insert “ / “ between every parts. for example: P3055LDG/G12345601/GGG2301/2000 DPI (Dots per inch): Over 300 dpi Code : Code 128 Height: 6 mm at least